What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	18
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16ka301-e-ss

Pin Diagrams

44-Pin TQFP/QFN[1,2,3]

Pin	Pin Features	
	PIC24FVXXKA304	**PIC24FXXKA304**
1	SDA1/T1CK/$\overline{\text{U1RTS}}$/CTED4/CN21/RB9	SDA1/T1CK/$\overline{\text{U1RTS}}$/CTED4/CN21/RB9
2	U1RX/CN18/RC6	U1RX/CN18/RC6
3	U1TX/CN17/RC7	U1TX/CN17/RC7
4	OC2/CN20/RC8	OC2/CN20/RC8
5	IC2/CTED7/CN19/RC9	IC2/CTED7/CN19/RC9
6	IC1/CTED3/CN9/RA7	IC1/CTED3/CN9/RA7
7	**VCAP**	**C2OUT/OC1/CTED1/INT2/CN8/RA6**
8	PGED2/SDI1/CTED11/CN16/RB10	PGED2/SDI1/CTED11/CN16/RB10
9	PGEC2/SCK1/CTED9/CN15/RB11	PGEC2/SCK1/CTED9/CN15/RB11
10	**AN12/HLVDIN/CTED2/INT2/CN14/RB12**	**AN12/HLVDIN/CTED2/CN14/RB12**
11	AN11/SDO1/CTPLS/CN13/RB13	AN11/SDO1/CTPLS/CN13/RB13
12	OC3/CN35/RA10	OC3/CN35/RA10
13	IC3/CTED8/CN36/RA11	IC3/CTED8/CN36/RA11
14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/RB14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/RB14
15	AN9/C3INA/T3CK/T2CK/REFO/$\overline{\text{SS1}}$/CTED6/CN11/RB15	AN9/C3INA/T3CK/T2CK/REFO/$\overline{\text{SS1}}$/CTED6/CN11/RB15
16	VSS/AVSS	VSS/AVSS
17	VDD/AVDD	VDD/AVDD
18	$\overline{\text{MCLR}}$/VPP/RA5	$\overline{\text{MCLR}}$/VPP/RA5
19	VREF+/CVREF+/AN0/C3INC/CTED1/CN2/RA0	VREF+/CVREF+/AN0/C3INC/CN2/RA0
20	CVREF-/VREF-/AN1/CN3/RA1	CVREF-/VREF-/AN1/CN3/RA1
21	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0
22	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1
23	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/CTED13/CN6/RB2	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/CTED13/CN6/RB2
24	AN5/C1INA/C2INC/SCL2/CN7/RB3	AN5/C1INA/C2INC/SCL2/CN7/RB3
25	AN6/CN32/RC0	AN6/CN32/RC0
26	AN7/CN31/RC1	AN7/CN31/RC1
27	AN8/CN10/RC2	AN8/CN10/RC2
28	VDD	VDD
29	VSS	VSS
30	OSCI/AN13/CLKI/CN30/RA2	OSCI/AN13/CLKI/CN30/RA2
31	OSCO/AN14/CLKO/CN29/RA3	OSCO/AN14/CLKO/CN29/RA3
32	OCFB/CN33/RA8	OCFB/CN33/RA8
33	SOSCI/AN15/$\overline{\text{U2RTS}}$/CN1/RB4	SOSCI/AN15/$\overline{\text{U2RTS}}$/CN1/RB4
34	SOSCO/SCLKI/$\overline{\text{U2CTS}}$/CN0/RA4	SOSCO/SCLKI/$\overline{\text{U2CTS}}$/CN0/RA4
35	$\overline{\text{SS2}}$/CN34/RA9	$\overline{\text{SS2}}$/CN34/RA9
36	SDI2/CN28/RC3	SDI2/CN28/RC3
37	SDO2/CN25/RC4	SDO2/CN25/RC4
38	SCK2/CN26/RC5	SCK2/CN26/RC5
39	VSS	VSS
40	VDD	VDD
41	PGED3/ASDA1[2]/CN27/RB5	PGED3/ASDA1[2]/CN27/RB5
42	PGEC3/ASCL1[2]/CN24/RB6	PGEC3/ASCL1[2]/CN24/RB6
43	C2OUT/OC1/INT0/CN23/RB7	INT0/CN23/RB7
44	SCL1/$\overline{\text{U1CTS}}$/C3OUT/CTED10/CN22/RB8	SCL1/$\overline{\text{U1CTS}}$/C3OUT/CTED10/CN22/RB8

Legend: Pin numbers in **bold** indicate pin function differences between PIC24FV and PIC24F devices.

Note 1: Exposed pad on underside of device is connected to VSS.

2: Alternative multiplexing for SDA1 (ASDA1) and SCL1 (ASCL1) when the I2CSEL Configuration bit is set.

3: PIC24F32KA304 device pins have a maximum voltage of 3.6V and are not 5V tolerant.

The internal oscillator block also provides a stable reference source for the Fail-Safe Clock Monitor (FSCM). This option constantly monitors the main clock source against a reference signal provided by the internal oscillator and enables the controller to switch to the internal oscillator, allowing for continued low-speed operation or a safe application shutdown.

1.1.4 EASY MIGRATION

Regardless of the memory size, all the devices share the same rich set of peripherals, allowing for a smooth migration path as applications grow and evolve.

The consistent pinout scheme used throughout the entire family also helps in migrating to the next larger device. This is true when moving between devices with the same pin count, or even jumping from 20-pin or 28-pin devices to 44-pin/48-pin devices.

The PIC24F family is pin compatible with devices in the dsPIC33 family, and shares some compatibility with the pinout schema for PIC18 and dsPIC30. This extends the ability of applications to grow from the relatively simple, to the powerful and complex.

1.2 Other Special Features

- **Communications:** The PIC24FV32KA304 family incorporates a range of serial communication peripherals to handle a range of application requirements. There is an I^2C™ module that supports both the Master and Slave modes of operation. It also comprises UARTs with built-in IrDA® encoders/decoders and an SPI module.
- **Real-Time Clock/Calendar:** This module implements a full-featured clock and calendar with alarm functions in hardware, freeing up timer resources and program memory space for use of the core application.
- **12-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, and faster sampling speed. The 16-deep result buffer can be used either in Sleep to reduce power, or in Active mode to improve throughput.
- **Charge Time Measurement Unit (CTMU) Interface:** The PIC24FV32KA304 family includes the new CTMU interface module, which can be used for capacitive touch sensing, proximity sensing, and also for precision time measurement and pulse generation.

1.3 Details on Individual Family Members

Devices in the PIC24FV32KA304 family are available in 20-pin, 28-pin, 44-pin and 48-pin packages. The general block diagram for all devices is shown in Figure 1-1.

The devices are different from each other in four ways:

1. Flash program memory (16 Kbytes for PIC24FV16KA devices, 32 Kbytes for PIC24FV32KA devices).
2. Available I/O pins and ports (18 pins on two ports for 20-pin devices, 22 pins on two ports for 28-pin devices and 38 pins on three ports for 44/48-pin devices).
3. Alternate SCLx and SDAx pins are available only in 28-pin, 44-pin and 48-pin devices and not in 20-pin devices.
4. Members of the PIC24FV32KA301 family are available as both standard and high-voltage devices. High-voltage devices, designated with an “FV” in the part number (such as PIC24FV32KA304), accommodate an operating VDD range of 2.0V to 5.5V, and have an on-board Voltage Regulator that powers the core. Peripherals operate at VDD. Standard devices, designated by “F” (such as PIC24F32KA304), function over a lower VDD range of 1.8V to 3.6V. These parts do not have an internal regulator, and both the core and peripherals operate directly from VDD.

All other features for devices in this family are identical; these are summarized in Table 1-1.

A list of the pin features available on the PIC24FV32KA304 family devices, sorted by function, is provided in Table 1-3.

Note:	Table 1-1 provides the pin location of individual peripheral features and not how they are multiplexed on the same pin. This information is provided in the pinout diagrams on pages 3, 4, 5, 6 and 7 of the data sheet. Multiplexed features are sorted by the priority given to a feature, with the highest priority peripheral being listed first.

TABLE 1-3: PIC24FV32KA304 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	F Pin Number 20-Pin PDIP/SSOP/SOIC	F 28-Pin SPDIP/SSOP/SOIC	F 28-Pin QFN	F 44-Pin QFN/TQFP	F 48-Pin UQFN	FV Pin Number 20-Pin PDIP/SSOP/SOIC	FV 28-Pin SPDIP/SSOP/SOIC	FV 28-Pin QFN	FV 44-Pin QFN/TQFP	FV 48-Pin UQFN	I/O	Buffer	Description
CN23	11	16	13	43	47	11	16	13	43	47	I	ST	Interrupt-on-Change Inputs
CN24	—	15	12	42	46	—	15	12	42	46	I	ST	
CN25	—	—	—	37	40	—	—	—	37	40	I	ST	
CN26	—	—	—	38	41	—	—	—	38	41	I	ST	
CN27	—	14	11	41	45	—	14	11	41	45	I	ST	
CN28	—	—	—	36	39	—	—	—	36	39	I	ST	
CN29	8	10	7	31	34	8	10	7	31	34	I	ST	
CN30	7	9	6	30	33	7	9	6	30	33	I	ST	
CN31	—	—	—	26	28	—	—	—	26	28	I	ST	
CN32	—	—	—	25	27	—	—	—	25	27	I	ST	
CN33	—	—	—	32	35	—	—	—	32	35	I	ST	
CN34	—	—	—	35	38	—	—	—	35	38	I	ST	
CN35	—	—	—	12	13	—	—	—	12	13	I	ST	
CN36	—	—	—	13	14	—	—	—	13	14	I	ST	
CVREF	17	25	22	14	15	17	25	22	14	15	I	ANA	Comparator Voltage Reference Output
CVREF+	2	2	27	19	21	2	2	27	19	21	I	ANA	Comparator Reference Positive Input Voltage
CVREF-	3	3	28	20	22	3	3	28	20	22	I	ANA	Comparator Reference Negative Input Voltage
CTCMP	4	4	1	21	23	4	4	1	21	23	I	ANA	CTMU Comparator Input
CTED1	14	20	17	7	7	11	2	27	19	21	I	ST	CTMU Trigger Edge Inputs
CTED2	15	23	20	10	11	15	23	20	10	11	I	ST	
CTED3	—	19	16	6	6	—	19	16	6	6	I	ST	
CTED4	13	18	15	1	1	13	18	15	1	1	I	ST	
CTED5	17	25	22	14	15	17	25	22	14	15	I	ST	
CTED6	18	26	23	15	16	18	26	23	15	16	I	ST	
CTED7	—	—	—	5	5	—	—	—	5	5	I	ST	
CTED8	—	—	—	13	14	—	—	—	13	14	I	ST	
CTED9	—	22	19	9	10	—	22	19	9	10	I	ST	
CTED10	12	17	14	44	48	12	17	14	44	48	I	ST	
CTED11	—	21	18	8	9	—	21	18	8	9	I	ST	
CTED12	5	5	2	22	24	5	5	2	22	24	I	ST	
CTED13	6	6	3	23	25	6	6	3	23	25	I	ST	

REGISTER 3-2: CORCON: CPU CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/C-0, HSC	R/W-0	U-0	U-0
—	—	—	—	IPL3(1)	PSV	—	—
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit(1)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit
1 = Program space is visible in data space
0 = Program space is not visible in data space

bit 1-0 **Unimplemented:** Read as ‘0’

Note 1: User interrupts are disabled when IPL3 = 1.

3.3 Arithmetic Logic Unit (ALU)

The PIC24F ALU is 16 bits wide and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are 2’s complement in nature. Depending on the operation, the ALU may affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as $\overline{\text{Borrow}}$ and $\overline{\text{Digit Borrow}}$ bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array, or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

The PIC24F CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware division for 16-bit divisor.

3.3.1 MULTIPLIER

The ALU contains a high-speed, 17-bit x 17-bit multiplier. It supports unsigned, signed or mixed sign operation in several multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

10.2.2 IDLE MODE

Idle mode has these features:

- The CPU will stop executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.6 “Selective Peripheral Module Control”**).
- If the WDT or FSCM is enabled, the LPRC will also remain active.

The device will wake from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle, the clock is re-applied to the CPU and instruction execution begins immediately, starting with the instruction following the `PWRSAV` instruction or the first instruction in the ISR.

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a `PWRSAV` instruction will be held off until entry into Sleep or Idle mode has completed. The device will then wake-up from Sleep or Idle mode.

10.2.4 DEEP SLEEP MODE

In PIC24FV32KA304 family devices, Deep Sleep mode is intended to provide the lowest levels of power consumption available without requiring the use of external switches to completely remove all power from the device. Entry into Deep Sleep mode is completely under software control. Exit from Deep Sleep mode can be triggered from any of the following events:

- POR Event
- $\overline{\text{MCLR}}$ Event
- RTCC Alarm (if the RTCC is present)
- External Interrupt 0
- Deep Sleep Watchdog Timer (DSWDT) Time-out
- Ultra Low-Power Wake-up (ULPWU) Event

In Deep Sleep mode, it is possible to keep the device Real-Time Clock and Calendar (RTCC) running without the loss of clock cycles.

The device has a dedicated Deep Sleep Brown-out Reset (DSBOR) and a Deep Sleep Watchdog Timer Reset (DSWDT) for monitoring voltage and time-out events. The DSBOR and DSWDT are independent of the standard BOR and WDT used with other power-managed modes (Sleep, Idle and Doze).

10.2.4.1 Entering Deep Sleep Mode

Deep Sleep mode is entered by setting the DSEN bit in the DSCON register and then executing a Sleep command (`PWRSAV #SLEEP_MODE`). An unlock sequence is required to set the DSEN bit. Once the DSEN bit has been set, there is no time limit before the `SLEEP` command can be executed. The DSEN bit is automatically cleared when exiting the Deep Sleep mode.

> **Note:** To re-enter Deep Sleep after a Deep Sleep wake-up, allow a delay of at least 3 TCY after clearing the RELEASE bit.

The sequence to enter Deep Sleep mode is:

1. If the application requires the Deep Sleep WDT, enable it and configure its clock source. For more information on Deep Sleep WDT, see **Section 10.2.4.5 “Deep Sleep WDT”**.
2. If the application requires Deep Sleep BOR, enable it by programming the DSLPBOR Configuration bit (FDS<6>).
3. If the application requires wake-up from Deep Sleep on RTCC alarm, enable and configure the RTCC module For more information on RTCC, see **Section 19.0 “Real-Time Clock and Calendar (RTCC)”**.
4. If needed, save any critical application context data by writing it to the DSGPR0 and DSGPR1 registers (optional).
5. Enable Deep Sleep mode by setting the DSEN bit (DSCON<15>).

> **Note:** An unlock sequence is required to set the DSEN bit.

6. Enter Deep Sleep mode by issuing a `PWRSAV #0` instruction.

Any time the DSEN bit is set, all bits in the DSWAKE register will be automatically cleared.

To set the DSEN bit, the unlock sequence in Example 10-2 is required:

EXAMPLE 10-2: THE UNLOCK SEQUENCE

```
//Disable Interrupts For 5 instructions
asm   volatile("disi #5");
//Issue Unlock Sequence
asm   volatile
mov   #0x55, W0;
mov   W0, NVMKEY;
mov   #0xAA, W1;
mov   W1, NVMKEY;
bset  DSCON, #DSEN
```

11.0 I/O PORTS

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the I/O Ports, refer to the *"PIC24F Family Reference Manual"*, **Section 12. "I/O Ports with Peripheral Pin Select (PPS)"** (DS39711). Note that the PIC24FV32KA304 family devices do not support Peripheral Pin Select features.

All of the device pins (except VDD and VSS) are shared between the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

11.1 Parallel I/O (PIO) Ports

A parallel I/O port that shares a pin with a peripheral is, in general, subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through", in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 11-1 illustrates how ports are shared with other peripherals and the associated I/O pin to which they are connected.

When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin may be read, but the output driver for the parallel port bit will be disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin may be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the Data Latch register (LAT), read the latch. Writes to the latch, write the latch. Reads from the port (PORT), read the port pins; writes to the port pins, write the latch.

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. That means the corresponding LATx and TRISx registers, and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

> **Note:** The I/O pins retain their state during Deep Sleep. They will retain this state at wake-up until the software restore bit (RELEASE) is cleared.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE

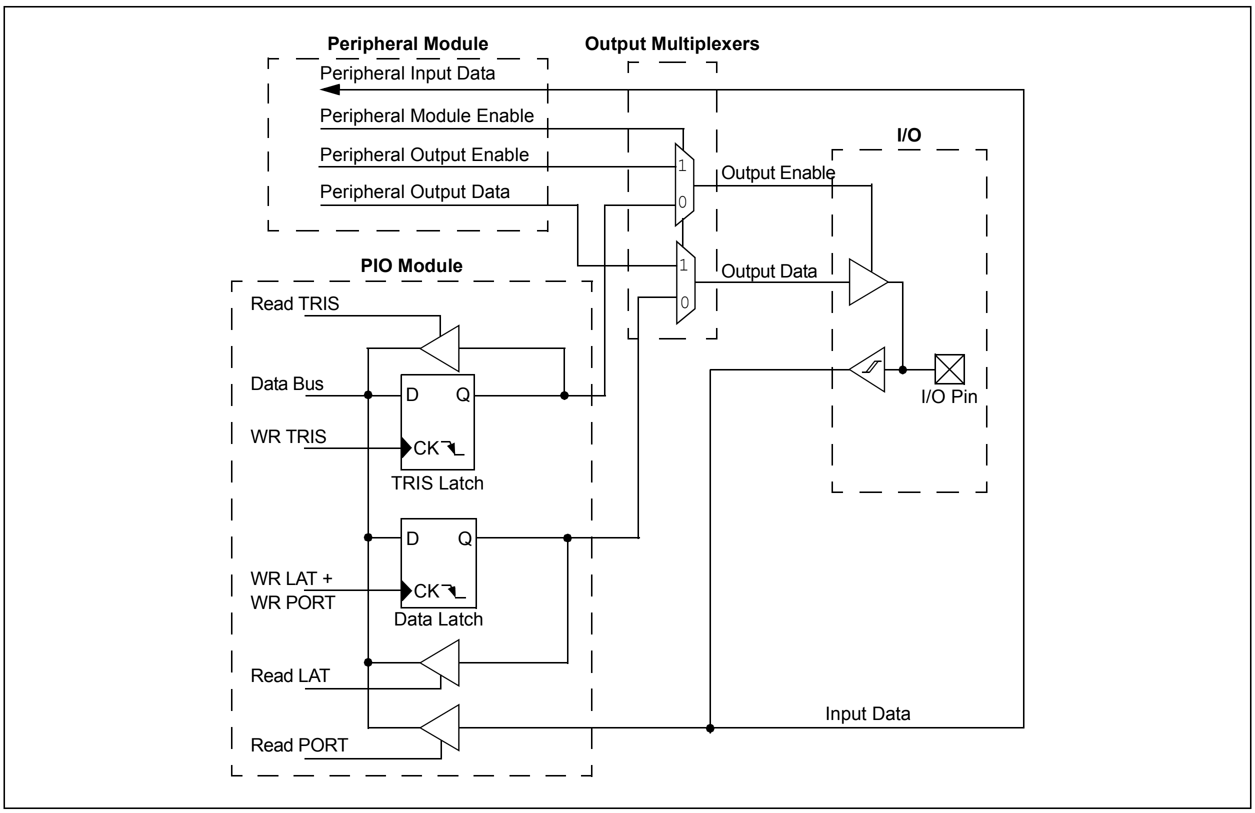


FIGURE 13-2: TIMER2 AND TIMER4 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM

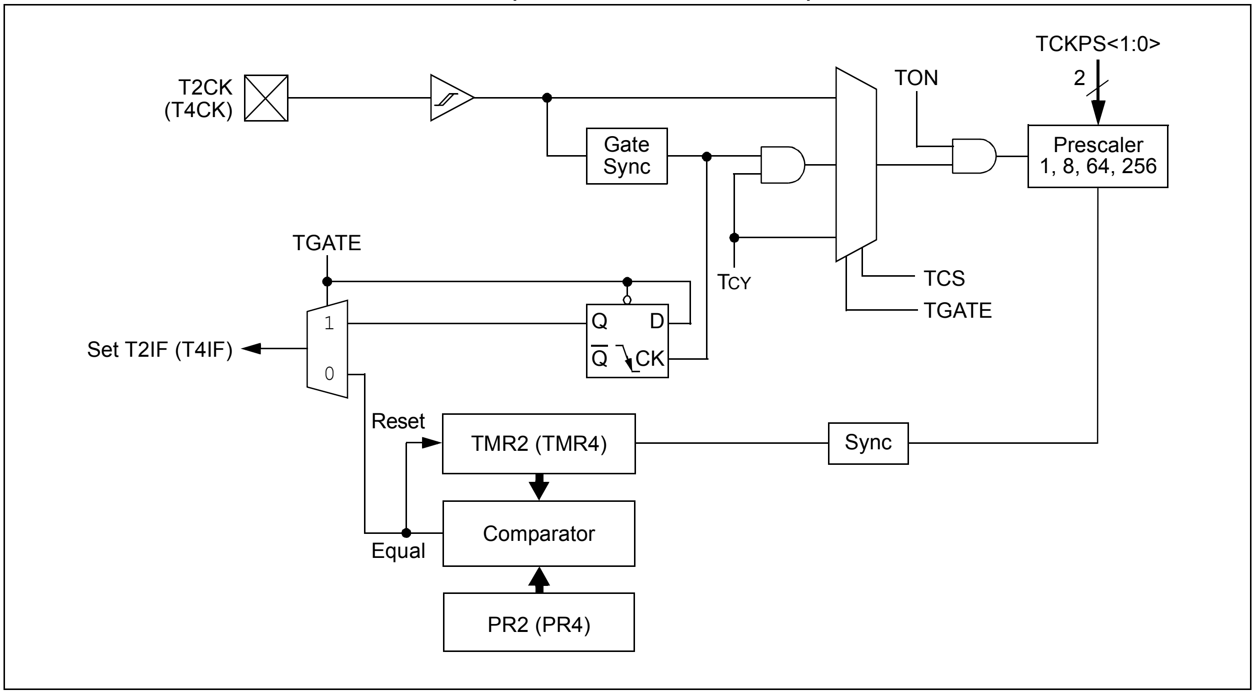
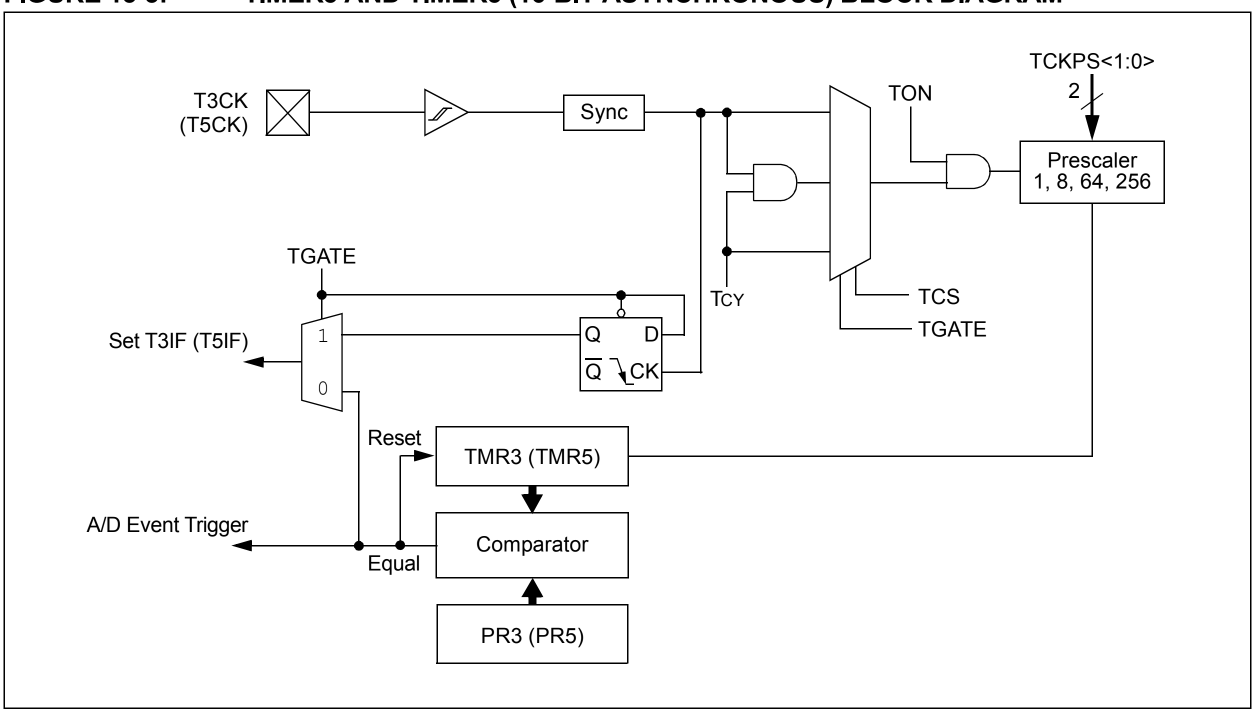


FIGURE 13-3: TIMER3 AND TIMER5 (16-BIT ASYNCHRONOUS) BLOCK DIAGRAM



14.0 INPUT CAPTURE WITH DEDICATED TIMERS

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **Section 34. "Input Capture with Dedicated Timer"** (DS39722).

All devices in the PIC24FV32KA304 family feature three independent input capture modules. Each of the modules offers a wide range of configuration and operating options for capturing external pulse events, and generating interrupts.

Key features of the input capture module include:

- Hardware-configurable for 32-bit operation in all modes by cascading two adjacent modules
- Synchronous and Trigger modes of output compare operation, with up to 20 user-selectable Sync/trigger sources available
- A 4-level FIFO buffer for capturing and holding timer values for several events
- Configurable interrupt generation
- Up to 6 clock sources available for each module, driving a separate internal 16-bit counter

The module is controlled through two registers: ICxCON1 (Register 14-1) and ICxCON2 (Register 14-2). A general block diagram of the module is shown in Figure 14-1.

14.1 General Operating Modes

14.1.1 SYNCHRONOUS AND TRIGGER MODES

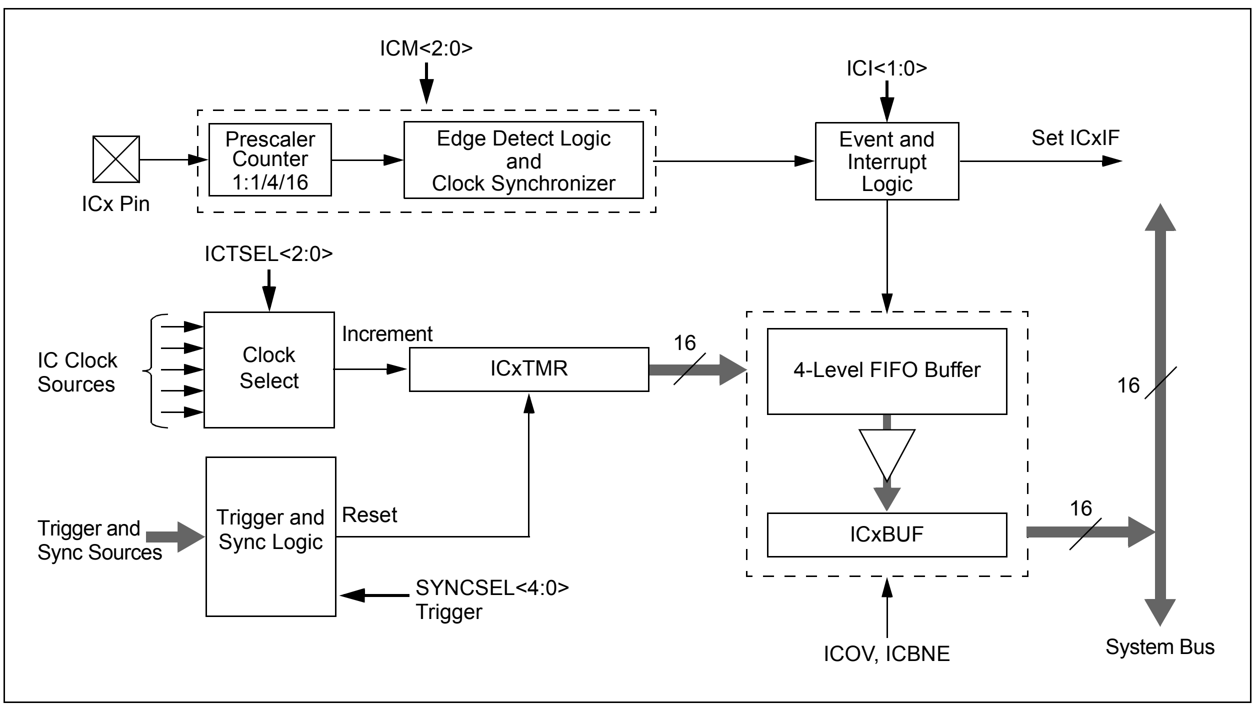
By default, the input capture module operates in a Free-Running mode. The internal 16-bit counter, ICxTMR, counts up continuously, wrapping around from FFFFh to 0000h on each overflow, with its period synchronized to the selected external clock source. When a capture event occurs, the current 16-bit value of the internal counter is written to the FIFO buffer.

In Synchronous mode, the module begins capturing events on the ICx pin as soon as its selected clock source is enabled. Whenever an event occurs on the selected Sync source, the internal counter is reset. In Trigger mode, the module waits for a Sync event from another internal module to occur before allowing the internal counter to run.

Standard, free-running operation is selected by setting the SYNCSELx bits to '`00000`' and clearing the ICTRIG bit (ICxCON2<7>). Synchronous and Trigger modes are selected any time the SYNCSELx bits are set to any value except '`00000`'. The ICTRIG bit selects either Synchronous or Trigger mode; setting the bit selects Trigger mode operation. In both modes, the SYNCSELx bits determine the Sync/trigger source.

When the SYNCSELx bits are set to '`00000`' and ICTRIG is set, the module operates in Software Trigger mode. In this case, capture operations are started by manually setting the TRIGSTAT bit (ICxCON2<6>).

FIGURE 14-1: INPUT CAPTURE x BLOCK DIAGRAM



EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPIx CLOCK SPEED(1)

$$F_{SCK} = \frac{F_{CY}}{\text{Primary Prescaler * Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCKx FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	**2:1**	**4:1**	**6:1**	**8:1**
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.
2: SCKx frequencies are indicated in kHz.

REGISTER 17-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	AMSK9	AMSK8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
AMSK7	AMSK6	AMSK5	AMSK4	AMSK3	AMSK2	AMSK1	AMSK0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as ‘0’

bit 9-0 **AMSK<9:0>:** Mask for Address Bit x Select bits
1 = Enables masking for bit x of an incoming message address; bit match is not required in this position
0 = Disables masking for bit x; bit match is required in this position

REGISTER 17-4: PADCFG1: PAD CONFIGURATION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	—	SMBUSDEL2	SMBUSDEL1	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5 **SMBUSDEL2:** SMBus SDA2 Input Delay Select bit
1 = The I2C2 module is configured for a longer SMBus input delay (nominal 300 ns delay)
0 = The I2C2 module is configured for a legacy input delay (nominal 150 ns delay)

bit 4 **SMBUSDEL1:** SMBus SDA1 Input Delay Select bit
1 = The I2C1 module is configured for a longer SMBus input delay (nominal 300 ns delay)
0 = The I2C1 module is configured for a legacy input delay (nominal 150 ns delay)

bit 3-0 **Unimplemented:** Read as ‘0’

19.2.6 ALRMVAL REGISTER MAPPINGS

REGISTER 19-8: ALMTHDY: ALARM MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month’s Tens Digit bit
Contains a value of ‘0’ or ‘1’.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month’s Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day’s Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 19-9: ALWDHR: ALARM WEEKDAY AND HOURS VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-8 **WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits
Contains a value from 0 to 6.

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **HRTEN<1:0>:** Binary Coded Decimal Value of Hour’s Tens Digit bits
Contains a value from 0 to 2.

bit 3-0 **HRONE<3:0>:** Binary Coded Decimal Value of Hour’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 19-10: ALMINSEC: ALARM MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0
bit 15							bit 8

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘0’
bit 14-12	**MINTEN<2:0>:** Binary Coded Decimal Value of Minute’s Tens Digit bits Contains a value from 0 to 5.
bit 11-8	**MINONE<3:0>:** Binary Coded Decimal Value of Minute’s Ones Digit bits Contains a value from 0 to 9.
bit 7	**Unimplemented:** Read as ‘0’
bit 6-4	**SECTEN<2:0>:** Binary Coded Decimal Value of Second’s Tens Digit bits Contains a value from 0 to 5.
bit 3-0	**SECONE<3:0>:** Binary Coded Decimal Value of Second’s Ones Digit bits Contains a value from 0 to 9.

NOTES:

REGISTER 26-9: DEVID: DEVICE ID REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 23							bit 16

R	R	R	R	R	R	R	R
FAMID7	FAMID6	FAMID5	FAMID4	FAMID3	FAMID2	FAMID1	FAMID0
bit 15							bit 8

R	R	R	R	R	R	R	R
DEV7	DEV6	DEV5	DEV4	DEV3	DEV2	DEV1	DEV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 23-16 **Unimplemented:** Read as ‘0’

bit 15-8 **FAMID<7:0>:** Device Family Identifier bits

01000101 = PIC24FV32KA304 family

bit 7-0 **DEV<7:0>:** Individual Device Identifier bits

00010111 = PIC24FV32KA304
00000111 = PIC24FV16KA304
00010011 = PIC24FV32KA302
00000011 = PIC24FV16KA302
00011001 = PIC24FV32KA301
00001001 = PIC24FV16KA301

00010110 = PIC24F32KA304
00000110 = PIC24F16KA304
00010010 = PIC24F32KA302
00000010 = PIC24F16KA302
00011000 = PIC24F32KA301
00001000 = PIC24F16KA301

26.4 Deep Sleep Watchdog Timer (DSWDT)

In PIC24FV32KA304 family devices, in addition to the WDT module, a DSWDT module is present which runs while the device is in Deep Sleep, if enabled. It is driven by either the SOSC or LPRC oscillator. The clock source is selected by the Configuration bit, DSWDTOSC (FDS<4>).

The DSWDT can be configured to generate a time-out, at 2.1 ms to 25.7 days, by selecting the respective postscaler. The postscaler can be selected by the Configuration bits, DSWDTPS<3:0> (FDS<3:0>). When the DSWDT is enabled, the clock source is also enabled.

DSWDT is one of the sources that can wake-up the device from Deep Sleep mode.

26.5 Program Verification and Code Protection

For all devices in the PIC24FV32KA304 family, code protection for the boot segment is controlled by the Configuration bit, BSS0, and the general segment by the Configuration bit, GSS0. These bits inhibit external reads and writes to the program memory space This has no direct effect in normal execution mode.

Write protection is controlled by bit, BWRP, for the boot segment and bit, GWRP, for the general segment in the Configuration Word. When these bits are programmed to '0', internal write and erase operations to program memory are blocked.

26.6 In-Circuit Serial Programming

PIC24FV32KA304 family microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock (PGECx) and data (PGEDx), and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

26.7 In-Circuit Debugger

When MPLAB® ICD 3, MPLAB REAL ICE™ or PICkit™ 3 is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the PGECx and PGEDx pins.

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{\text{MCLR}}$, V_{DD}, V_{SS}, PGECx, PGEDx and the pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins.

30.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

Data for VDD levels greater than 3.3V are applicable to PIC24FV32KA304 family devices only.

30.1 Characteristcs for Industrial Temperature Devices (-40°C to +85°C)

FIGURE 30-1: TYPICAL AND MAXIMUM IDD vs. FOSC (EC MODE, 2 MHz TO 32 MHz, -40°C TO +85°C)

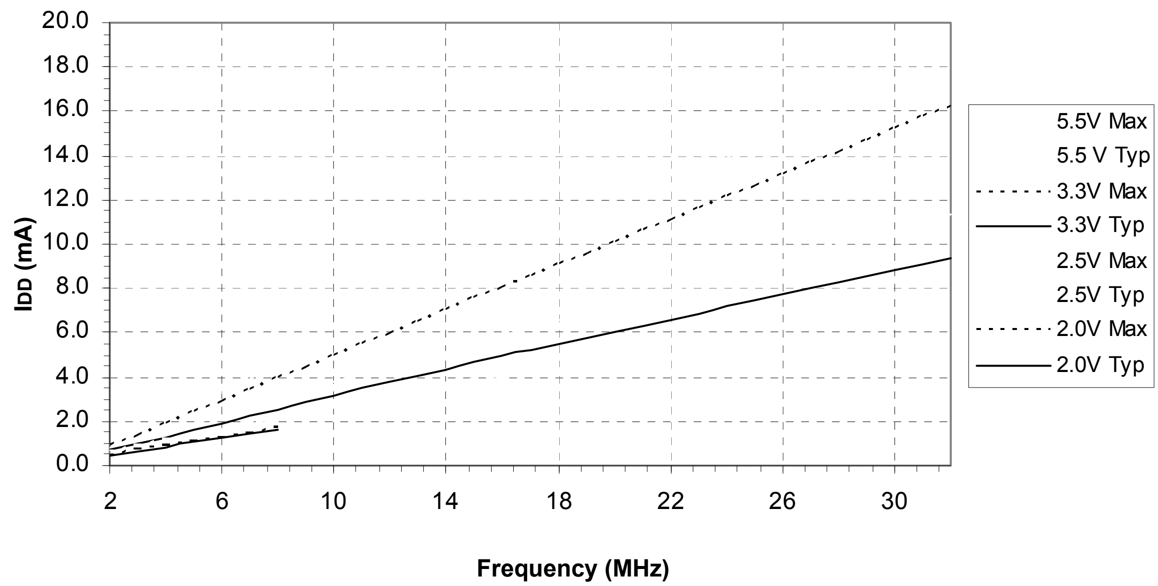


FIGURE 30-2: TYPICAL AND MAXIMUM IDD vs. FOSC (EC MODE, 1.95 kHz TO 1 MHz, +25°C)

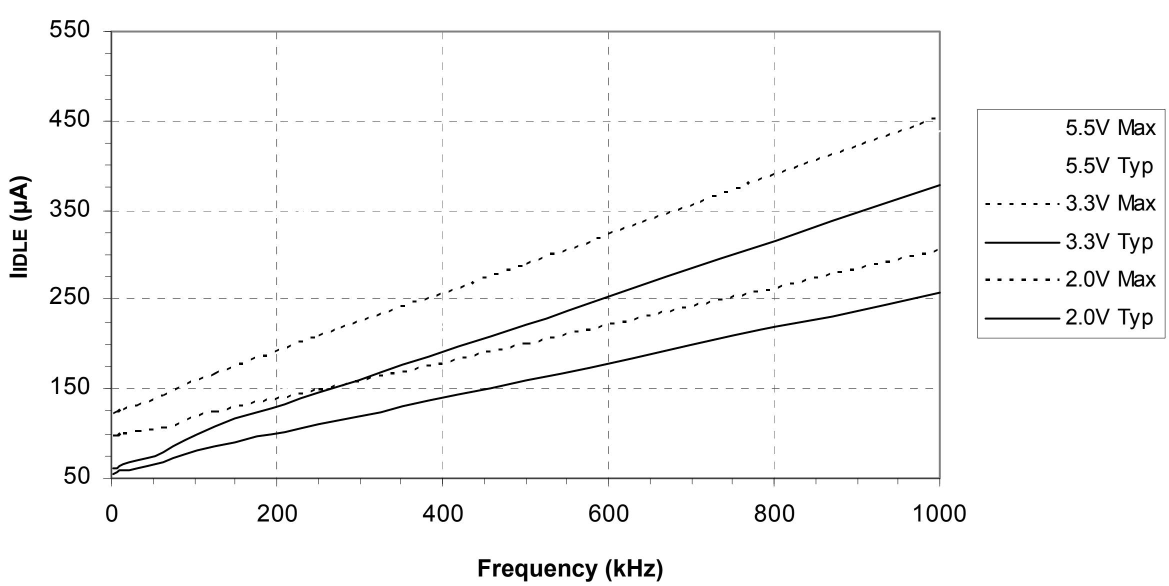


FIGURE 30-3: TYPICAL AND MAXIMUM IIDLE vs. FREQUENCY (EC MODE, 2 MHz TO 32 MHz)

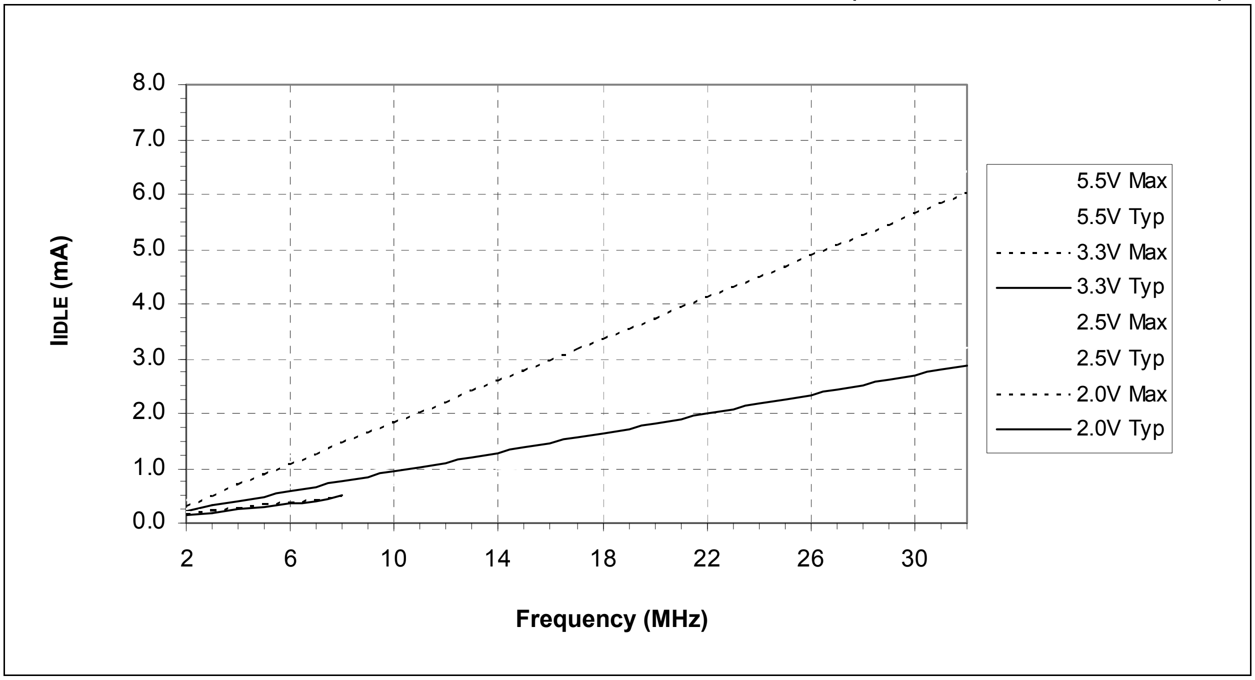
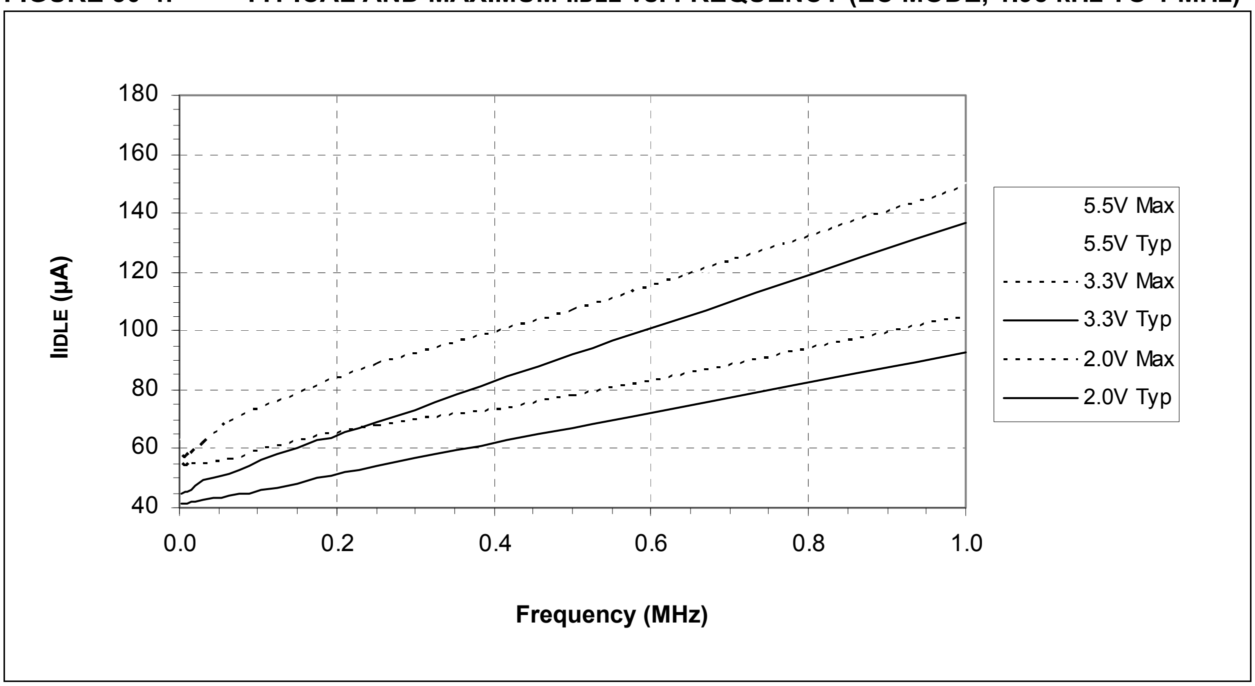


FIGURE 30-4: TYPICAL AND MAXIMUM IIDLE vs. FREQUENCY (EC MODE, 1.95 kHz TO 1 MHz)

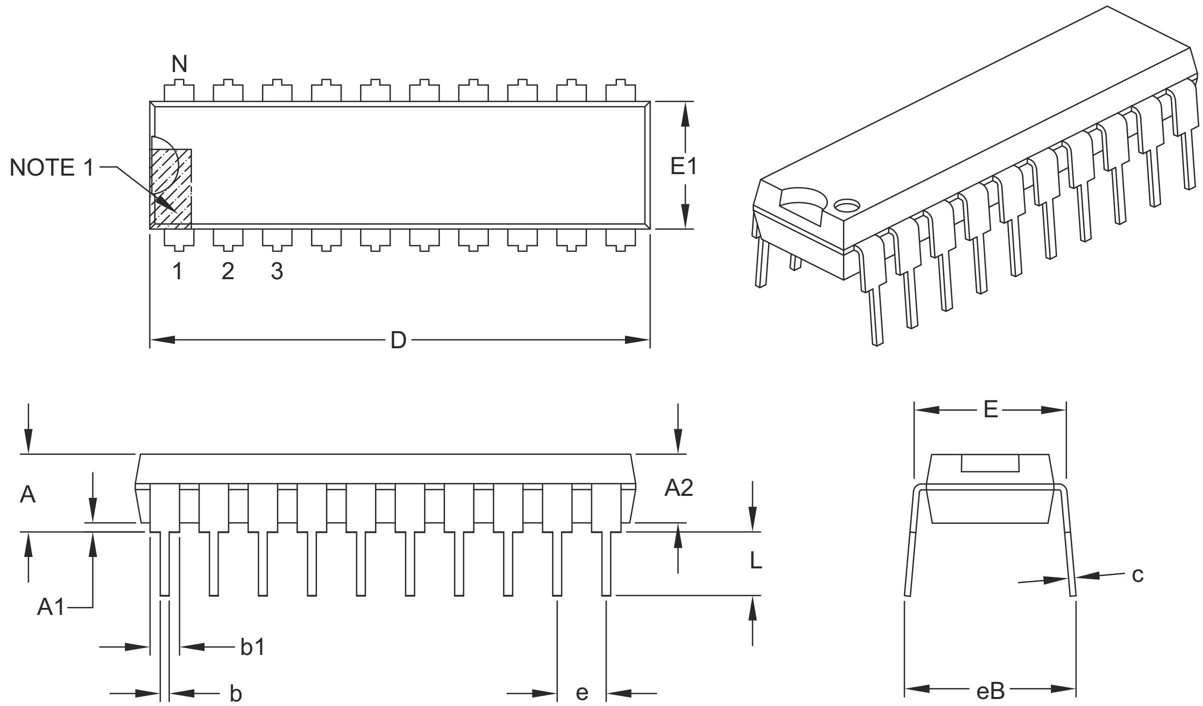


31.2 Package Details

The following sections give the technical details of the packages.

20-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



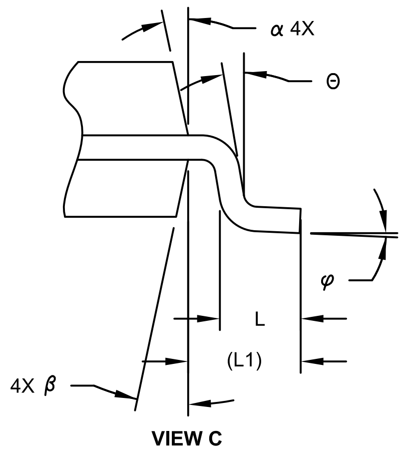
	Units	INCHES		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.980	1.030	1.060
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

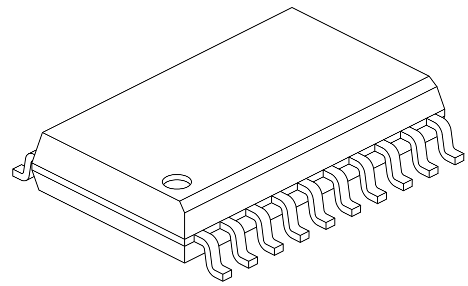
Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-019B

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	12.80 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

APPENDIX A: REVISION HISTORY

Revision A (March 2011)

Original data sheet for the PIC24FV32KA304 family of devices.

Revision B (April 2011)

Section 25.0 "Charge Time Measurement Unit (CTMU)" was revised to change the description of the IRNGx bits in CTMUICON (Register 25-3). Setting '01' is the base current level (0.55 μA nominal) and setting '00' is 1000x base current.

Section 29.0 "Electrical Characteristics" was revised to change the following typical I_{PD} specifications:

- DC20h/i/j/k from 204 μA to 200 μA
- DC60h/i/j/k from 0.15 μA to 0.025 μA
- DC60l/m/n/o from 0.25 μA to 0.040 μA
- DC72h/i/j/k from 0.80 μA to 0.70 μA

Revision C (April 2012)

Updated the Pin Diagrams on Pages 3 through 7, to change "LVDIN" to "HLVDIN" in all occurrences, and correct the placement of certain functions.

Updated Table 1-3 to remove references to unimplemented package types, corrected several erroneous pin assignments and removed other alternate but unimplemented assignments.

For **Section 5.0 "Flash Program Memory"**, updated Example 5-2, Example 5-3 and Example 5-4 with new table offset functions.

Updated Figure 12-1 to correctly show the implemented Timer1 input options.

For **Section 22.0 "12-Bit A/D Converter with Threshold Detect"**:

- Updated Register 22-1 to add the MODE12 bit
- Updated the descriptions of the PVCFGx and CSCNA bits in Register 22-2
- Updated Register 22-4 to change the VRSREQ bit to a reserved bit position
- Modified footnote text in Register 22-5
- Corrected C_{HOLD} in Figure 22-2

For **Section 25.0 "Charge Time Measurement Unit (CTMU)"**:

- Updated the text in **Section 25.1 "Measuring Capacitance"** and **Section 25.3 "Pulse Generation and Delay"** to better reflect the module's implementation
- Updated Figure 25-3 to show additional detail in pulse generation

Added the following timing diagrams and timing requirement tables to **Section 29.0 "Electrical Characteristics"**:

- Figure 29-6 (Reset, Watchdog Timer, Oscillator Start-up Timer and Power-up Timer Timing Characteristics)
- Figure 29-7 (Brown-out Reset Characteristics)
- Figure 29-9 (Input Capture x Timings) through Figure 29-21 (SPIx Module Slave Mode Timing Characteristics (CKE = 1))
- Table 29-28 (Input Capture x Requirements) through Table 29-39 (SPIx Module Slave Mode Timing Requirements (CKE = 1))
- Figure 29-22 (A/D Conversion Timing)

Updated Table 29-5 to add specification, DC15.

Replaced Table 29-6, Table 29-7 and Table 29-8 with new, shorter versions that remove unimplemented temperature options. (No existing specification values have been changed in this process.)

Updated Table 29-16 with correct values for CTMUICON bit settings.

Combined previous Table 29-21 and Table 29-22 to create a new Table 29-21 (AC Characteristics: Internal RC Accuracy). All existing subsequent tables are renumbered accordingly.

Updated Table 29-26 to add specifications, SY35 and SY55.

Updated Table 29-40:

- Split AD01 into separate entries for "F" and "FV" device families
- Added specifications, AD08 (I_{VREF}) and AD09 (Z_{VREF})
- Changed AD17 (2.5 kΩ max. to 1 kΩ max.)

Updated Table 29-41:

- Changed AD50 (75 ns min. to 600 ns min.)
- Changed AD51 (250 ns typ. to 1.67 μs typ.)
- Changed AD60 (0.5 T_{AD} min. to 2 T_{AD} min.)
- Split AD55 into separate entries for 10-bit and 12-bit conversions

Added **Section 30.0 "DC and AC Characteristics Graphs and Tables"**, with Figure 30-1 through Figure 30-39.

Replaced some of the packaging diagrams in **Section 31.0 "Packaging Information"** with the newly revised diagrams.

Other minor typographic corrections throughout.